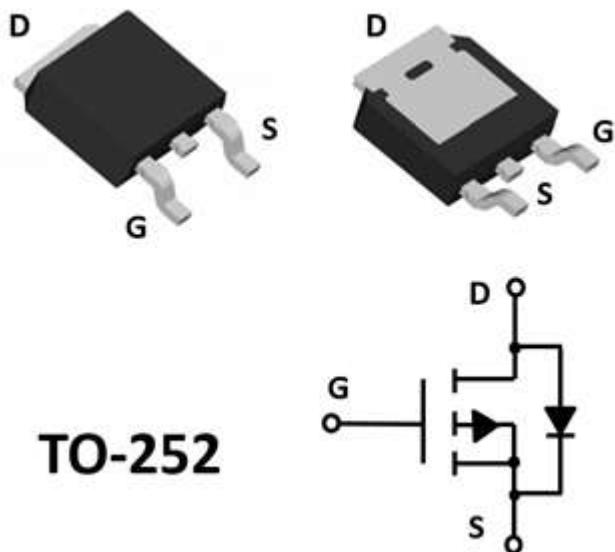




P-Channel Enhancement Mode Field Effect Transistor



Product Summary

- V_{DS} -60V
- I_D -25A
- $R_{DS(ON)}$ (at $V_{GS}=-10V$) <50 mohm
- $R_{DS(ON)}$ (at $V_{GS}=-4.5V$) <65 mohm
- 100% UIS Tested
- 100% ∇V_{DS} Tested

General Description

- Split gate trench MOSFET technology
- Low $R_{DS(on)}$ & FOM
- Low C_{rss}
- Extremely low switching loss
- Excellent stability and uniformity

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Industrial and Motor Drive applications

■ Absolute Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source Voltage		V_{DS}	-60	V
Gate-source Voltage		V_{GS}	± 20	V
Drain Current	$T_c=25^\circ\text{C}$	I_D	-25	A
	$T_c=100^\circ\text{C}$		-16	
Pulsed Drain Current ^A		I_{DM}	-100	A
Avalanche energy ^B		E_{AS}	49	mJ
Total Power Dissipation ^C	$T_c=25^\circ\text{C}$	P_D	72	W
	$T_c=100^\circ\text{C}$		28.8	
Junction and Storage Temperature Range		T_J, T_{STG}	-55~+150	$^\circ\text{C}$

■ Thermal resistance

Parameter		Symbol	Typ	Max	Units
Thermal Resistance Junction-to-Ambient ^D	$t \leq 10\text{S}$	$R_{\theta JA}$	15	20	$^\circ\text{C/W}$
Thermal Resistance Junction-to-Ambient ^D	Steady-State		40	50	
Thermal Resistance Junction-to-Case	Steady-State	$R_{\theta JC}$	1.35	1.7	

■ Ordering Information (Example)

PREFERRED P/N	PACKING CODE	Marking	MINIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON QUANTITY(pcs)	DELIVERY MODE
YJD25GP06A	F1	YJD25GP06A	2500	2500	25000	13" reel



YJD25GP06A

■ Electrical Characteristics (T_J=25°C unless otherwise noted)

Parameter	Symbol	Conditions		Min	Typ	Max	Units
Static Parameter							
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V, I _D =-250μA		-60			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-60V, V _{GS} =0V	T _J =25℃			-1	μA
			T _J =55℃			-5	
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} =0V				±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D =-250μA		-1.3	-1.8	-2.5	V
Static Drain-Source On-Resistance	R _{DS(on)}	V _{GS} = -10V, I _D =-20A			38	50	mΩ
		V _{GS} = -4.5V, I _D =-10A			48	65	
Gate Resistance	R _g	f=1MHz, Open Drain			12		Ω
Diode Forward Voltage	V _{SD}	I _S =-20A, V _{GS} =0V			-0.95	-1.3	V
Maximum Body-Diode Continuous Current	I _S					-25	A
Dynamic Parameters							
Input Capacitance	C _{iss}	V _{DS} =-30V, V _{GS} =0V, f=1MHZ			1100		pF
Output Capacitance	C _{oss}				350		
Reverse Transfer Capacitance	C _{rss}				28		
Switching Parameters							
Total Gate Charge	Q _g (-10V)	V _{GS} =-10V, V _{DS} =-30V, I _D =-20A			18.7		nC
Total Gate Charge	Q _g (-4.5V)				8.8		
Gate-Source Charge	Q _{gs}				4.7		
Gate-Drain Charge	Q _{gd}				3.0		
Reverse Recovery Chrage	Q _{rr}	I _F =-20A, di/dt=100A/us			8.2		ns
Reverse Recovery Time	t _{rr}				20.2		
Turn-on Delay Time	t _{D(on)}	V _{GS} =-10V, V _{DD} =-30V, I _D =-12A R _{GEN} =6Ω			7.5		
Turn-on Rise Time	t _r				39.5		
Turn-off Delay Time	t _{D(off)}				43.6		
Turn-off fall Time	t _f				55.1		

A. Repetitive rating; pulse width limited by max. junction temperature.

B. V_{DD}=50V, R_G=25Ω, L=0.5mH, I_{AS}=14A.

C. Pd is based on max. junction temperature, using junction-case thermal resistance.

D. The value of R_{qJA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with T_A=25°C. The Power dissipation PDSM is based on R_{qJA} ≤ 10s and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.



■ Typical Performance Characteristics

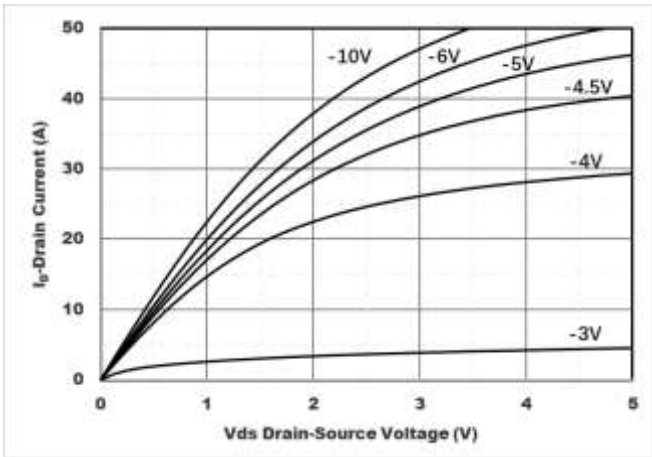


Figure1. Output Characteristics

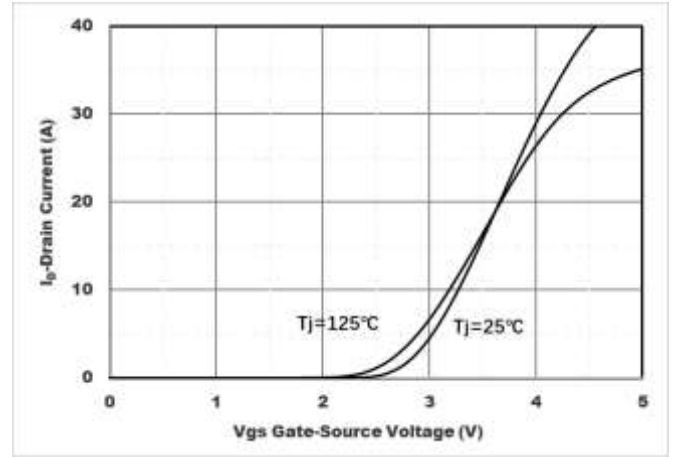


Figure2. Transfer Characteristics

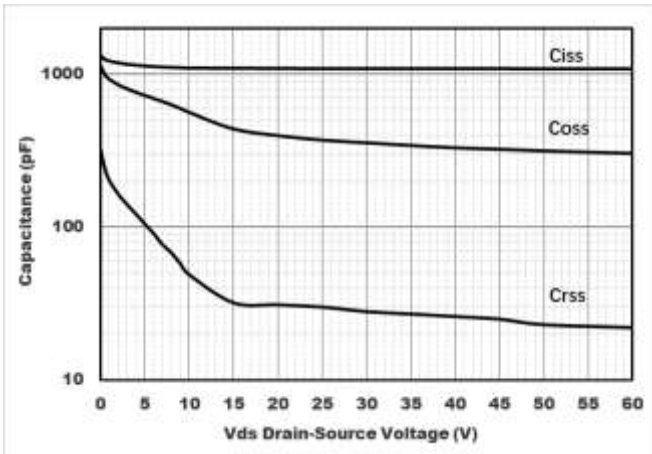


Figure3. Capacitance Characteristics

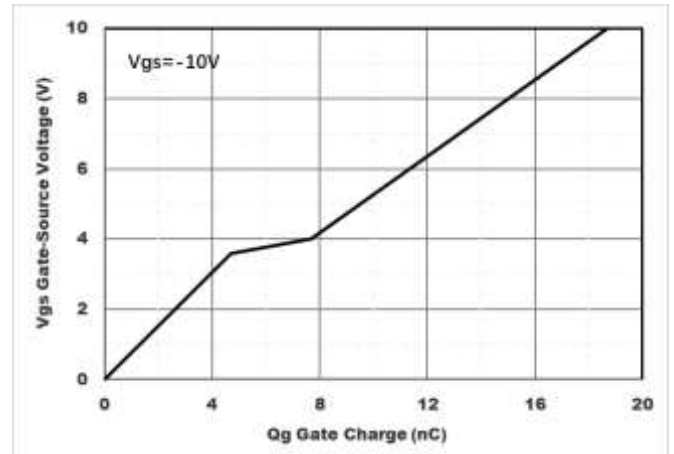


Figure4. Gate Charge

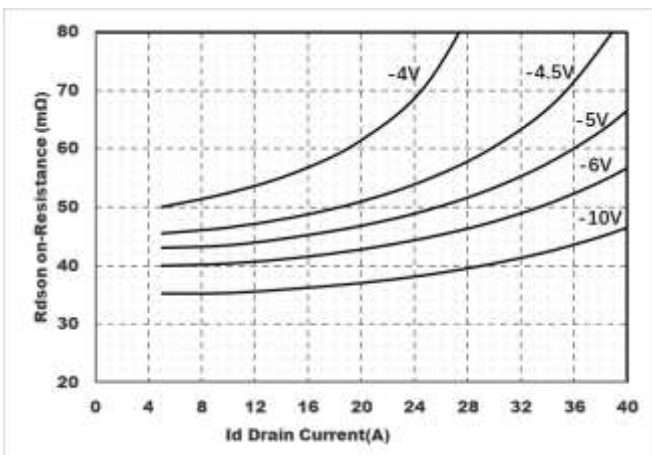


Figure5. : On-Resistance vs. Drain Current

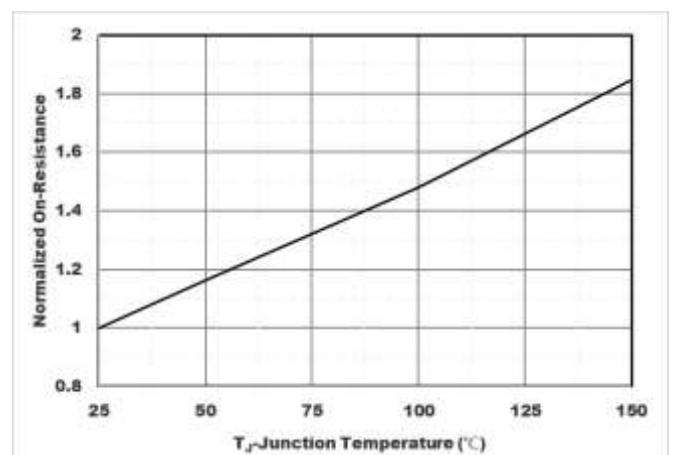


Figure6. Normalized On-Resistance

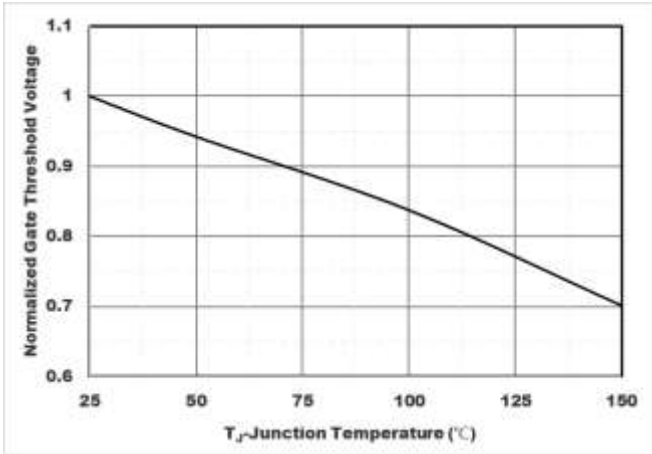


Figure7. Normalized Gate Threshold Voltage

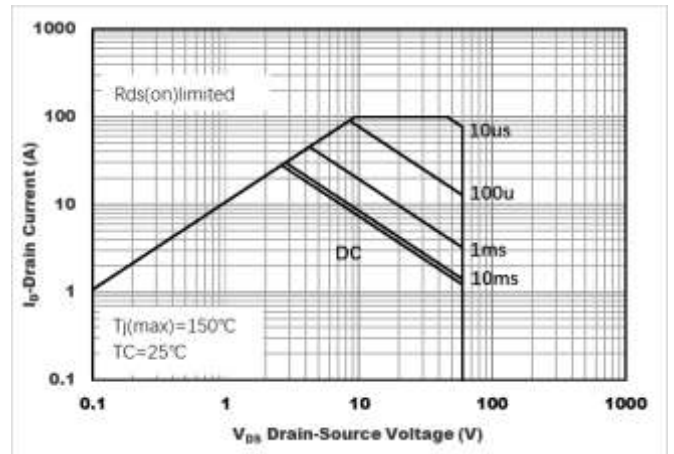


Figure8.Safe Operation Area

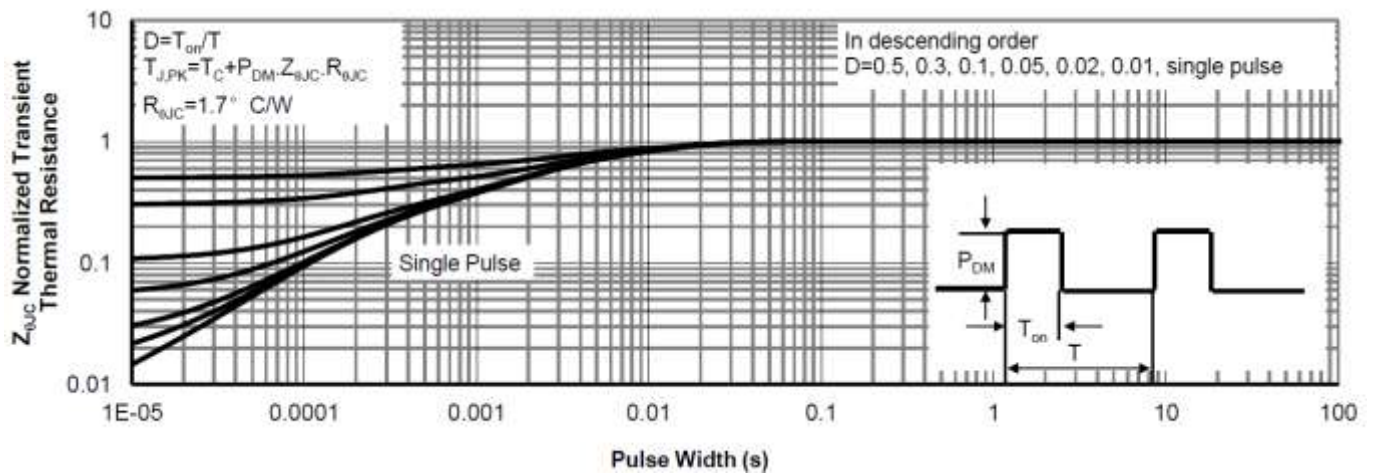
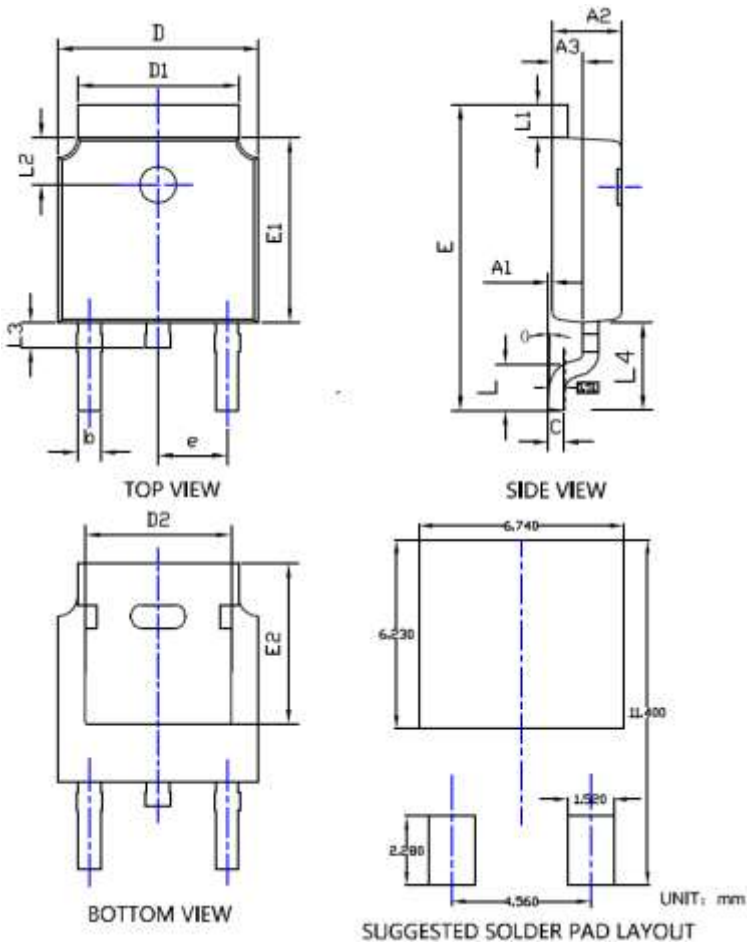


Figure9.Normalized Maximum Transient thermal impedance



YJD25GP06A

■ TO-252-B Package information



SYMBOL	DIMENSIONS					
	INCHES			Millimeter		
	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
A1	0.000	---	0.008	0.000	---	0.200
A2	0.087	0.091	0.094	2.200	2.300	2.400
A3	0.035	0.039	0.043	0.900	1.000	1.100
b	0.026	0.030	0.034	0.660	0.760	0.860
c	0.018	0.020	0.023	0.460	0.520	0.580
D	0.256	0.260	0.264	6.500	6.600	6.700
D1	0.203	0.209	0.215	5.150	5.300	5.450
D2	0.181	0.189	0.195	4.600	4.800	4.950
E	0.390	0.398	0.406	9.900	10.100	10.300
E1	0.236	0.240	0.244	6.000	6.100	6.200
E2	0.203	0.209	0.215	5.150	5.300	5.450
e	0.090BSC			2.286BSC		
L	0.049	0.059	0.069	1.250	1.500	1.750
L1	0.035	---	0.050	0.900	---	1.270
L2	0.055	---	0.075	1.400	---	1.900
L3	0.240	0.310	0.039	0.600	0.800	1.000
L4	0.114REF			2.900REF		
⌀	0°	---	10°	0°	---	10°

NOTE:

- 1.PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.
- 2.TOLERANCE 0.1mm UNLESS OTHERWISE SPECIFIED.
- 3.THE PAD LAYOUT IS FOR REFERENCE PURPOSES ONLY.



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